MICROCHIP

Semiconductor Device Type: MNY (5QX) 008 TDFN 2x3x0.8mm NiPdAu

Termination Base Alloy: Copper Alloy (Cu)

Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm
Silica, vitreous (or fused)	60676-86-0	Mold Compound	50.975	7.136	509,745
Epoxy Resin	Trade Secret	Mold Compound	5.217	0.730	52,174
Phenolic Resin	Trade Secret	Mold Compound	3.598	0.504	35,982
Carbon Black	1333-86-4	Mold Compound	0.180	0.025	1,799
Copper	7440-50-8	Lead Frame	32.712	4.580	327,123
Iron	7439-89-6	Lead Frame	0.773	0.108	7,733
Phosphorous	7723-14-0	Lead Frame	0.084	0.012	841
Zinc (Metal)	7440-66-0	Lead Frame	0.050	0.007	504
Silver	7440-22-4	Die Attach	0.936	0.131	9,360
Acrylate resins Proprietary	Trade Secret	Die Attach	0.216	0.030	2,160
Treated silica	Trade Secret	Die Attach	0.024	0.003	240
Heterocyclic organic compound	Trade Secret	Die Attach	0.024	0.003	240
Silicon	7440-21-3	Chip (Die)	4.010	0.561	40,100
Gold	7440-57-5	Wire Bond	0.770	0.108	7,700
Nickel	7440-02-0	Plating on external leads (pins)	0.412	0.058	4,116
Palladium	7440-05-3	Plating on external leads (pins)	0.014	0.002	139
Gold	7440-57-5	Plating on external leads (pins)	0.004	0.001	45
		TOTALS:	**100.000**	**14.000**	**1,000,000**

0.0140 g Total Mass

Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)

JEDEC 97 Product Marking and/or Pkg. Labeling e4

8.40	**(mg) Total**	**Mold Compound**	**% ot Total Weight**	**59.97**
	Silica, vitreous (or fused)	60676-86-0	85.00	
	Epoxy Resin	Trade Secret	8.70	
	Phenolic Resin	Trade Secret	6.00	
	Carbon Black	1333-86-4	0.30	
		Total	**100.00**	
4.71	**(mg) Total**	**Lead Frame**	**% of Total Weight**	**33.62**
	Copper	7440-50-8	97.30	
	Iron	7439-89-6	2.30	
	Phosphorous	7723-14-0	0.25	
	Zinc (Metal)	7440-66-0	0.15	
		Total	**100.00**	
0.17	**(mg) Total**	**Die Attach**	**% of Total Weight**	**1.2**
	Silver	7440-22-4	78.00	
	Acrylate resins Proprietary	Trade Secret	18.00	
	Treated silica	Trade Secret	2.00	
	Heterocyclic organic compound	Trade Secret	2.00	
		Total	**100.00**	
0.56	**Total (mg)**	**Chip (Die)**	**% of Total Weight**	**4.01**
	Doped Silicon	7440-21-3	100.00	
		Total	**100.00**	
0.11	**(mg) Total**	**Wire Bond**	**% of Total Weight**	**0.77**
	Doped Gold	7440-57-5	100.00	
		Total	**100.00**	
0.06	**(mg) Total**	**Plating on external leads (pins)**	**% of Total Weight**	**0.43**
	Nickel	7440-02-0	95.73	
	Palladium	7440-05-3	3.23	
	Gold	7440-57-5	1.04	
		Total	**100.00**	
14.000				**100.000**

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table